

IN THE SPECIFICATION

Paragraph starting at page 14, fifth line from the bottom:

Figs. 2A and 2B illustrate a second embodiment of the present invention, which employs a BGA structure. In the BGA structure of Figs. 2A and 2B, ~~[[a]]~~ the terminal ~~[[103]]~~ which is connected to an external circuit ~~includes~~ is embodied as a land 115 on which a metal ball, such as a solder ball, is disposed. Fig. 2A is a plan view of a TCP of the second embodiment and Fig. 2B is a sectional view taken along line C-C1 of Fig. 2A. A base film 101 is made of, for example, polyimide. Sprocket holes 102 are formed on the base film 101 to convey the same. As in the case of the first embodiment, the upper and the lower semiconductor elements 107 and 110 are substantially square-shaped, and the upper semiconductor element 107 is smaller than the lower semiconductor element 110. The tape carrier of the present embodiment may be applied to upper and lower semiconductor elements 107 and 110 of any shape, such as rectangular, by changing the arrangement of the inner lead portions formed on the base film 101. The upper semiconductor element 107 is aligned with the lower semiconductor element 110 so that corresponding edges of the two semiconductor elements 107 and 110 are parallel to each other. The upper semiconductor element 107 is stacked on and adhered to the lower semiconductor element 110 using an adhesive 109. The inner lead portion 105 is shorter than the inner lead portion 104.